



Material Content Data Sheet



Halogen-Free

Sales Product Name	IFX007T	Issued	24. June 2021
MA#	MA005551641		
Package	PG-TO263-7-1	Weight*	1535.89 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	4.086	0.27	0.27	2660	2660
chip_2	inorganic material	silicon	7440-21-3	1.916	0.12	0.12	1247	1247
chip_3	inorganic material	silicon	7440-21-3	1.212	0.08	0.08	789	789
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		158	
	non noble metal	iron	7439-89-6	0.810	0.05		527	
	non noble metal	copper	7440-50-8	808.613	52.64	52.71	526479	527164
wire	non noble metal	aluminium	7429-90-5	14.587	0.95	0.95	9498	9498
encapsulation	inorganic material	zinc oxide	1314-13-2	5.811	0.38		3784	
	miscellaneous	miscellaneous	-	23.245	1.51		15135	
	plastics	epoxy resin	-	87.170	5.68		56756	
	inorganic material	silicon dioxide	60676-86-0	464.909	30.27	37.84	302698	378373
lead finish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8488	8488
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	138	139
solder	non noble metal	tin	7440-31-5	0.066			43	
	noble metal	silver	7440-22-4	0.082	0.01		54	
	non noble metal	lead	7439-92-1	3.141	0.20	0.21	2045	2142
glue	plastics	Polyimide	26023-21-2	0.396	0.03	0.03	258	258
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			21	
	non noble metal	iron	7439-89-6	0.106	0.01		69	
	non noble metal	copper	7440-50-8	106.210	6.92	6.93	69152	69242
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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